

1. Reflow Soldering

Soldering must be carried out without exceeding the allowable soldering temperature and time shown within the shaded area of Figure "Allowable Temperature and Time of Reflow Soldering".

In case the soldering is repeated, the maximum time in Figure "Allowable Temperature and Time of Reflow Soldering" should be accumulated time. The standard soldering conditions are shown in Figure "Reflow Soldering Standard Conditions".

Follow standard solder stencil mask pattern to avoid the possibility of solder being trapped under connector.

2. Soldering by Soldering Iron

Soldering by soldering iron should be carried out in accordance to the following conditions.

Pre-heating	Temperature	150°C
	Time	60 to 120 s.
Soldering	Temperature (at the tip of the soldering iron)	less than 350°C
	Time	less than 3 s.

3. We cannot warrant against mishaps caused by any use of this product that deviates from allowable temperature and time of reflow soldering.

4. In soldering, do not apply excessive mechanical force to terminals or leads greater than specified in the drawing.

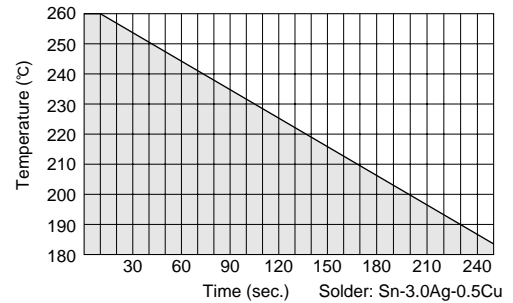
5. Please note the following in case of soldering terminals or leads of the product.

- (1) Use Rosin based flux, but not with strong acid flux (Chlorine content should be less than 0.20wt%).
- (2) Flux should be thoroughly cleaned from connector to prevent possible deterioration of electrical characteristics.

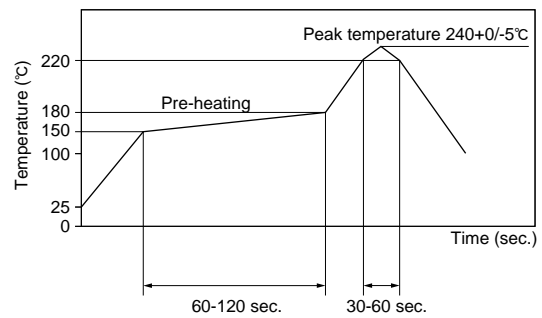
6. Please mount this product at the position so that stress by wrap and/or bend of the PCB may not apply to it.

7. Please avoid the cleaning of this product.

Allowable Temperature and Time of Reflow Soldering



Reflow Soldering Standard Conditions



Measuring point of temperature: In-Out Terminals of the Device
 Reflow Soldering: Both Convection and Infrared Rays
 : Hot Air
 : Hot Plate